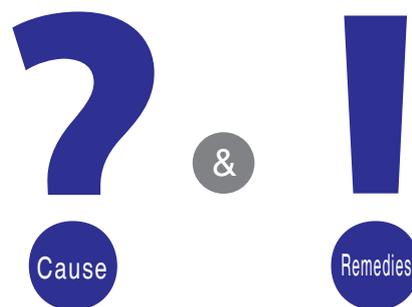




Troubleshooting case studies

[MOS FET Relay]

Relay Failures



Correctly obtaining the best performance from relays

When MOS FET relays are used under conditions that exceed the absolute maximum ratings even for a moment, it can be disruptive.

To ensure the reliability of the MOS FET relay, it is important for the users to carefully consider all environmental conditions - including de-rating design- when using the MOS FET relay.

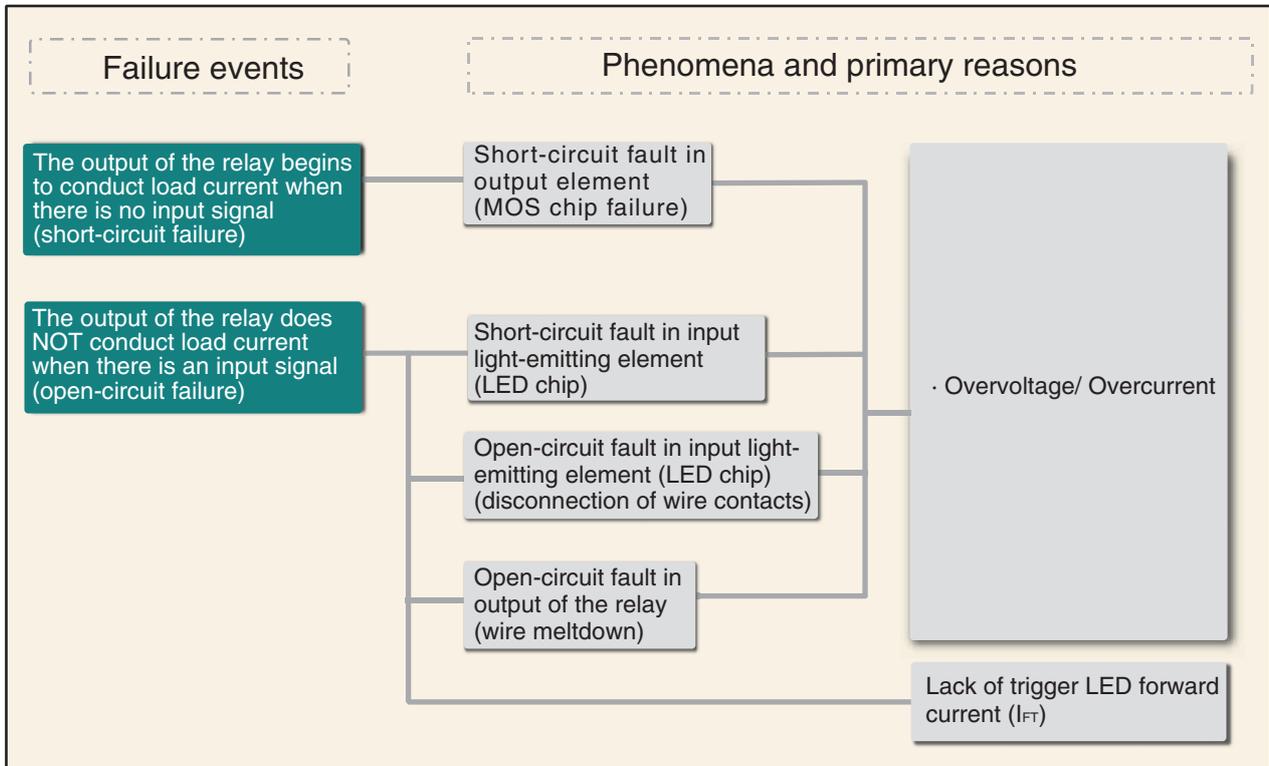
This brochure lists the causes and remedial measures from the past failure events as a guideline to help uncover any unexpected failure causes.

Contents

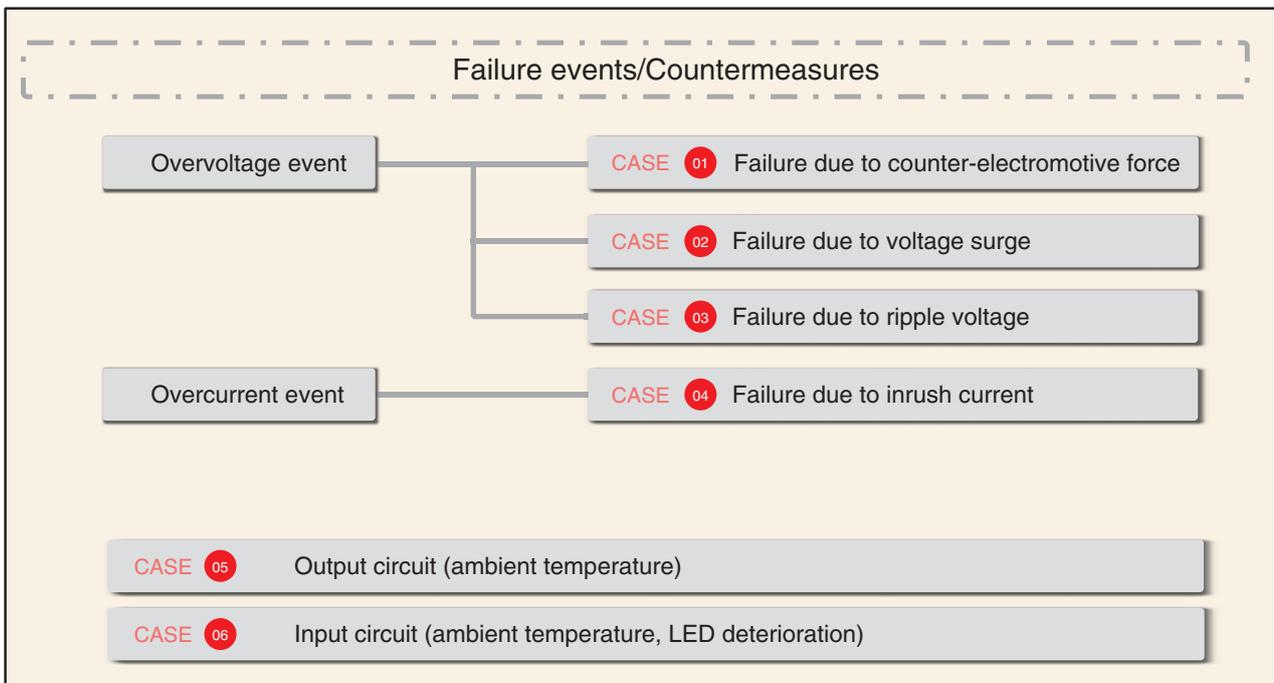
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Failure Relationship Diagrams

MOS FET relay - Failure Relationship Diagram



MOS FET Relay – Failure Events



Counter-Electromotive Force

When the counter-electromotive force generated from the interruption of inductive load (L) current (when MOS FET is turned OFF) exceeds the load voltage (V_{OFF}) of the MOS FET, it may cause damage to the output element.

Probable cause of failure

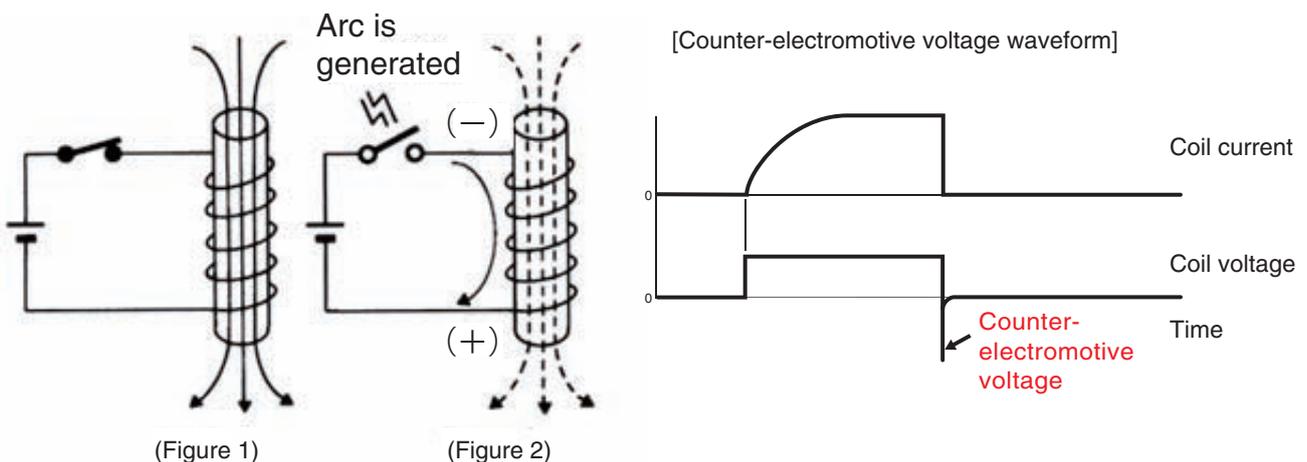
When the switch is turned OFF and power is cut off, the inductive load (L) will try to maintain the flow of the current and generate a voltage in opposite polarity to the voltage applied at both ends of the load. Such voltage is known as counter-electromotive force. When the force exceeds the load voltage (V_{OFF}) of MOS FET, it may damage the output element of MOS FET.

- Short-circuit fault in output element (refer to P15 *Photos of Failure Event*)
 - The output of the relay begins to conduct load current when the LED forward operating current (I_F) is NOT applied across the input terminals (short-mode failure)
- Open-circuit fault in output element (refer to P16 *Photos of Failure Event*)
 - The output of the relay does not conduct load current when the LED forward operating current (I_F) is applied across the input terminals (open-circuit failure)

The coil produces a magnetic flux when voltage is applied (Figure 1).

Once the switch is turned OFF, the magnetic field begins to collapse but the coil's self-induction action opposes this change in the magnetic field by producing a counter-electromotive force (Figure 2).

At this point, the switch is in open circuit preventing the electromotive force arising in the coil from escaping, ultimately producing an extremely high voltage.

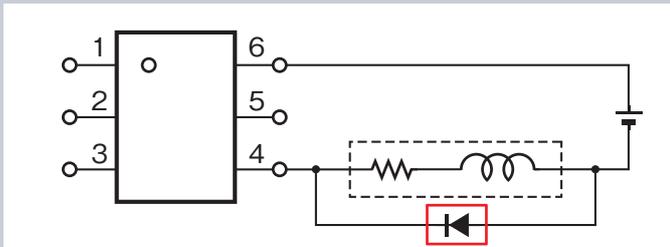


Example) Inductive loads with counter-electromotive force

Solenoid, electromagnetic valve, motor brakes, contactors, and mechanical relay etc.

**Connect overvoltage protective circuit (protection device) to prevent excess voltage produced in an inductive load.
(To protect from overvoltage exceeding the load voltage (V_{OFF}))**

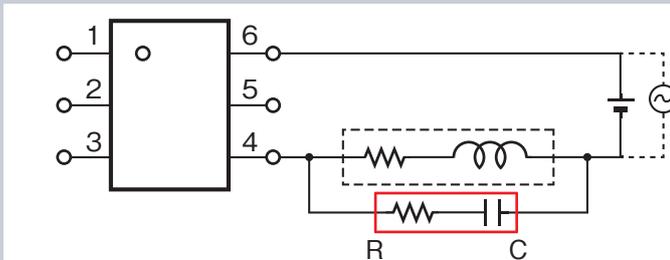
(1) Use external diode to absorb energy



Selection guideline:

The reverse breakdown voltage of the diode must be 10 times higher than the circuit voltage and the forward current as high as or higher than the load current.

(2) Use snubber circuit to absorb energy



Selection guideline:

Indicators for the capacitor and resistor values are as follows:

C: 0.5 to 1 μF for contact current (1 A)

R: 0.5 to 1 Ω for contact voltage (1 V)

The values may change according to the characteristics of the load.

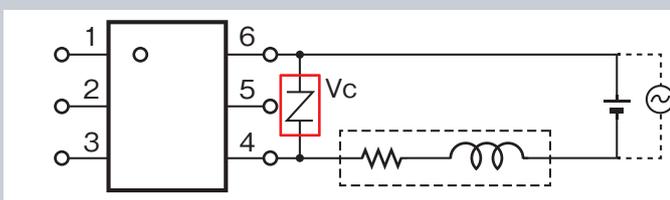
The capacitor suppresses the spark discharge of current when the contacts are open. The resistor limits the inrush current when the contacts are closed again.

These roles of capacitor and resistor must be considered when determining the ideal capacitance and resistance values by experimentation.

Use a capacitor that can withstand voltage of between 200 and 300 V. For AC circuit, use non-polarized capacitor (a condenser exclusively for AC).

When there is a problem to interrupt the arcs between the contacts at high DC voltage, in some cases, it is more effective in connecting the capacitor and resistor across the contacts rather than across the load. However, a test should be performed on the actual equipment to substantiate this.

(3) Use varistor to reduce overvoltage



Selection guideline:

The cutoff voltage (V_c) of the varistor must satisfy the following conditions. For AC, it must be multiplied by $\sqrt{2}$.

$V_c > (\text{supply voltage} \times 1.5)$

If V_c is set too high, the varistor may not be able to reduce high voltage as it should and result to less effect.

Remarks:

- Protection devices may delay the recovery (breaking time) on the load side. Make sure to perform a test under actual load condition to check the performance before actual use.
- Protection devices, including diode, snubber (C-R) and varistor must be installed as close as possible to either the load or MOS FET. Longer distance may affect the performance of the protection device.

Voltage Surge (Input Side)

When voltage surge, such as switching surge is applied to the input side of the MOS FET, it may cause damage to the input element.

Probable cause of failure

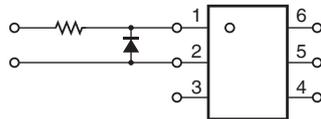
When backward voltage (surge reverse voltage) that exceeds the reverse voltage (V_R) of the LED is applied across the input terminals, it may damage the input light-emitting element (LED chip) ultimately causing malfunction.

- Short-circuit fault in LED chip (refer to P17 Photos of Failure Event)
 - The output of the relay does NOT conduct load current (does not turn ON) when LED forward operating current (I_F) is applied across the input terminals.
 - Open-circuit fault in LED chip (refer to P17 Photos of Failure Event)
 - The output of the relay does NOT conduct load current (does not turn ON) when LED forward operating current (I_F) is applied across the input terminals.
- * The substantial drop in light output prevents from switching to ON mode.

Countermeasure

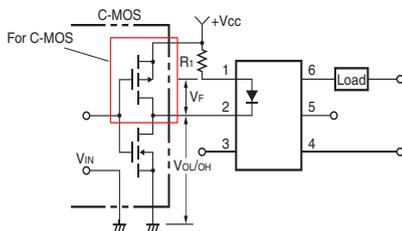
In the event of a backward voltage (surge reverse voltage) applied across the input terminals, place a diode antiparallel to the input terminal to prevent backward voltage that exceeds the reverse breakdown voltage (V_R) of the LED from being applied to the LED chip (Reference: 3 V or less)

Surge protection circuit (input side)

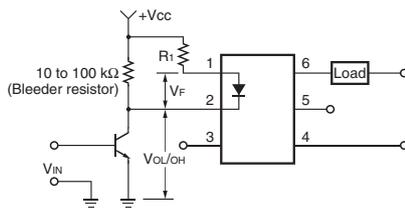


The following circuit is a representative example.

- Representative example of MOS FET relay drive circuit



Transistor



- To ensure reliable operation of the MOS FET relay, determine the limiting resistance value using the equation shown below when designing the circuit.

$$R1 = \frac{V_{CC} - V_{OL} - V_{F(ON)}}{I_{F(ON)}}$$

- * Make sure the $I_{F(ON)}$ is set at high value with safety margin. Refer to the catalogues of each model for the details of trigger LED forward operating current and recommended operating conditions of LED forward current.
- To ensure complete recovery of the MOS FET relay, calculate the value of release voltage using the equation shown below and make sure the voltage stays below the calculated value.

$$V_{F(OFF)} = V_{CC} - I_{F(OFF)}R1 - V_{OH}$$

- * Make sure the value of $I_{F(OFF)}$ is set lower than the release LED forward current indicated in the catalogues of each model and add safety margin.
- Add a bleeder resistor if the possible cause of the malfunction is coming from the leakage current in the transistor.

The CMOS drive circuit shown on the left is configured to have pins 1 and 2 maintained at approximately the same potential when switched to OFF mode, which offers exceptional noise immunity.

Voltage Surge (Output Side)

The effect of voltage surges (overvoltage conditions that exceed the absolute maximum rating even for a moment) on the MOS FET relay may cause damage to the output element.

Probable cause of failure

When the voltage surge superimposed on the output element (load circuit side) exceeds the load voltage V_{OFF} (absolute maximum rating), it may damage the output element of the MOS FET relay ultimately causing malfunction.

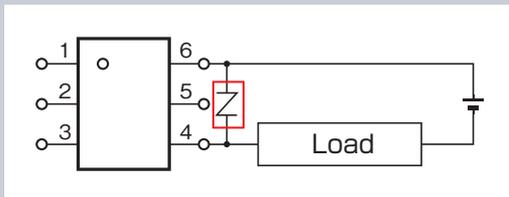
- Short-circuit fault in output element (refer to P15 *Photos of Failure Event*)
 - The output of the relay begins to conduct load current when LED forward operating current (I_F) is NOT applied across the input terminals (short-mode failure)
- Open-circuit fault in output element (refer to P16 *Photos of Failure Event*)
 - The output of the relay does NOT conduct load current when LED forward operating current (I_F) is applied across the input terminals (open-circuit failure)

Sources of voltage surge

- (1) Electro-static discharge: ESD (human contact, contact with equipment surfaces)
- (2) Transient originated from inside the electrical circuit or equipment
- (3) Lightning

Countermeasure

Connect varistor across the output side terminals



How to select the right varistor

The voltage of the varistor must not exceed the load voltage (V_{OFF}) of MOS FET relay.

- For ESD protection, multilayer chip varistor is most commonly used.
- Please refer to the following table of varistor guidance when using commercial AC power supply.

Varistor guidance

| Supply voltage | Recommended varistor voltage | Absolute maximum ratings V_{OFF} | Surge withstand capability |
|----------------|------------------------------|------------------------------------|----------------------------|
| 100 VAC line | 220 to 270 V | 400 to 600 V | 1000 A or more |
| 200 VAC line | 430 to 470 V | 600 V | 1000 A or more |

Ripple voltage

When the current exceeds the absolute maximum ratings (voltage or current) due to the ripple in power supply, it may damage both the input and output elements.

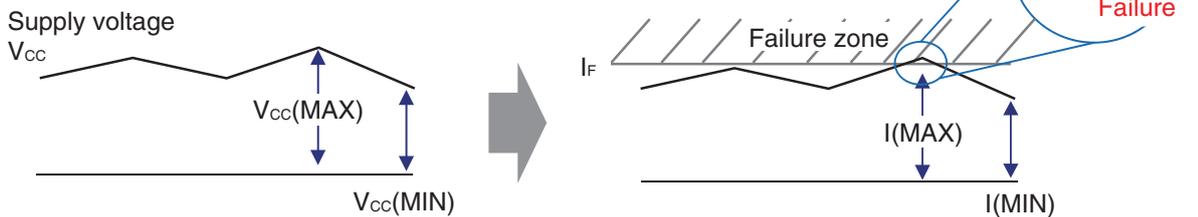
Probable cause of failure

Input side

When a current exceeding the maximum rated value of the LED forward current (I_F) flows across the input terminals affected by the maximum rated ripple of input voltage ($V_{CC}(\text{MAX})$), it may damage the input light-emitting element (LED chip) ultimately causing malfunction.

- Short-circuit fault in LED chip (refer to P17 *Photos of Failure Event*)
 - The output of the relay does NOT conduct load current (does not turn ON) when LED forward operating current (I_F) is applied across the input terminals.
- Open-circuit fault in LED chip (refer to P17 *Photos of Failure Event*)
 - The output of the relay does NOT conduct load current (does not turn ON) when LED forward operating current (I_F) is applied across the input terminals.
 - * The substantial drop in light output prevents from switching to ON mode.

[Example: Overcurrent exceeding I_F due to voltage ripple]



Countermeasure

Input ripple voltage must be considered to avoid exceeding the absolute maximum rated value of the LED forward current (I_F).

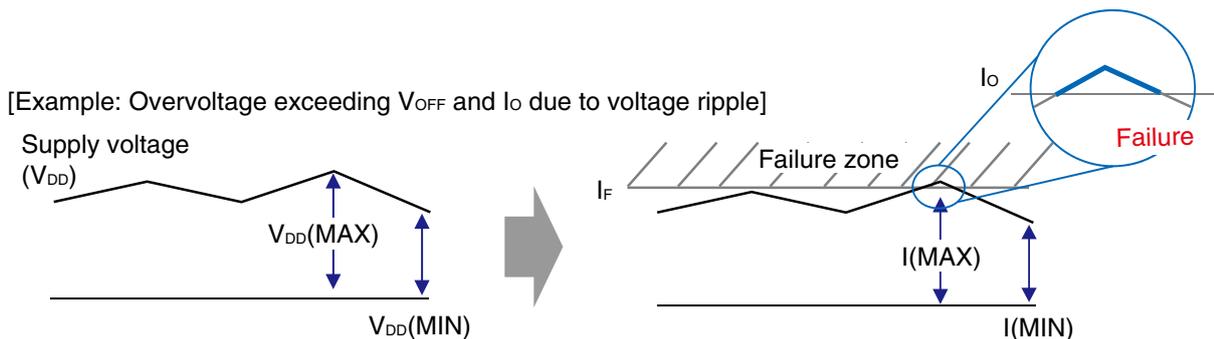
When the current exceeds the absolute maximum ratings (voltage or current) due to the ripple in power supply, it may damage both the input and output elements.

Probable cause of failure

Output side

When a voltage or current exceeding the absolute maximum rated values of output load voltage (V_{OFF}) and continuous load current (I_o) flows affected by the maximum rated ripple of input voltage ($V_{CC} (MAX)$), it may damage the output element ultimately causing malfunction.

- Short-circuit fault in output element (refer to P15 Photos of Failure Event)
 - The output of the relay begins to conduct load current when LED forward operating current (I_F) is NOT applied across the input terminals (short-mode failure)
- Open-circuit fault in output element (refer to P16 Photos of Failure Event)
 - The output of the relay does NOT conduct load current when LED forward operating current (I_F) is applied across the input terminals (open-circuit failure)



Countermeasure

Output ripple voltage must be considered to avoid exceeding the absolute maximum rated values of load voltage (V_{OFF}) and continuous load current (I_o).

Inrush current

Inrush current exceeding the absolute maximum rated value may occur when switching the MOS FET relay. This depends on the types of loads causing damage to the output element.

Probable cause of failure

Inrush current occurs when the MOS FET relay is switched. When the inrush current exceeds the pulse on-state current (I_{OP}) of the MOS FET relay, it may damage the output element.
(Pulse condition: $t=100$ ms, Duty=1/10)

The inrush current varies with the load type. Typical loads are indicated below.

1. Heater load (resistive load)

Resistive loads have very little inrush current (close to none). However, please note that resistance value varies with temperature in certain types of heaters, which may cause inrush current to occur under ambient temperature when the resistance value is low.

<Types of heater with possible inrush current>

- Pure metal heater (approximately 3 to 5 times of the rated current)
- Ceramic heater (approximately 3 to 5 times of the rated current)

2. Solenoid (only under AC power)

The inrush current is approximately 10 times the rated current.

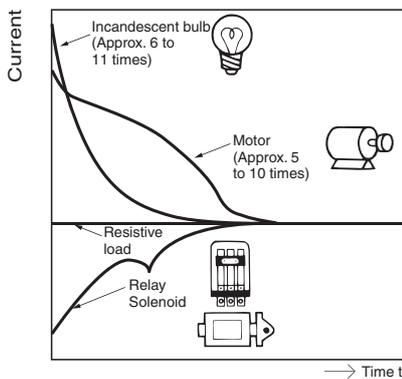
3. Mechanical relay (only under AC power)

The inrush current is approximately 2 to 3 times the rated current.

4. Motors

Inductive loads such as motors have inrush current of approximately 5 to 10 times the rated current at start-up.

DC loads and their inrush currents



AC loads and their inrush currents

| Load types | Inrush current/Steady state current | Waveform |
|-------------------|-------------------------------------|----------|
| Solenoid | Approx. 10 times | |
| Incandescent bulb | Approx. 10 to 15 times | |
| Motor | Approx. 5 to 10 times | |
| Relay | Approx. 2 to 3 times | |
| Capacitor | Approx. 20 to 50 times | |
| Resistive load | 1 | |

Countermeasure

Make sure to confirm the amount of inrush current that flows into the load and select a product that does not exceed the pulse on-state current (I_{OP}) of the MOS FET relay.

(Pulse condition: $t=100$ ms, Duty=1/10)

Output Circuit Design Guideline (Ambient Temperature)

Continuous load current on the output side (I_o) stipulates its reduction rate according to temperature. When the current exceeds the specified rate, it may damage the output element.

Probable cause of failure

The reduction rate of continuous load current (I_o), according to the increasing ambient temperature, is specified based on the connection temperature rating (T_j =Allowable temperature rating in which the connection of internal element can withstand). When a current flows into the output exceeding the specified rate under high temperature condition, the connection temperature surpasses its rating causing damage to the output element.

Case: Continuous load current (I_o) had flown into the output exceeding the specified rate under high temperature condition

(Case study)

We needed output current flow of 400 mA. So, we selected a 500 mA ($T_a=25^\circ\text{C}$) relay that allows the output side to have 25% margin of continuous load current (I_o).

The prototype test results were good, showing normal operation.

(The MOS FET relay during the trial test was used under room temperature of 25°C)

Malfunction occurred after the product was launched into the market.

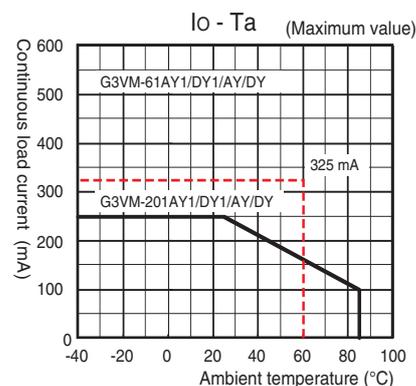
(Cause)

In actual use, the temperature around the MOS FET relay was 60°C , so the current was over the continuous load current (I_o) stipulated in the "Continuous load current - Ambient temperature" graph.

(Conclusion)

The specified continuous load current (I_o) changes according to ambient temperature as shown on the right graph.

According to the graph, the MOS FET relay used this time under the ambient temperature condition of 60°C should be 325 mA for continuous load current (I_o). With current of 400 mA, it exceeded its specified rate ultimately causing the product in the market to malfunction.



Please make sure to check the continuous load current rates in relation to ambient temperature specified for each model by referring to the Graph: *Continuous Load Current with Ambient Temperature* and select a suitable MOS FET relay (with safety margin) to make sure the product is used under the allowable room temperature of the relay.

Input Circuit Design Guideline (I_F)

Lack of LED forward operating current (I_F) caused by “drop in light output due to age-related degradation of input LED” of MOS FET relay and “increased room temperature” may cause the MOS FET relay to malfunction.

Probable cause of failure

The LED forward operating current (I_F) designed for the input circuit must be determined by considering several factors. These include: LED aging and temperature changes, as well as power supply variation with respect to the trigger LED forward current (I_{FT}). Otherwise, the input current will fall short due to the changes in environment and the amount of usage time, ultimately damaging the MOS FET relay. (Events of failure is shown on P13 and P14)

Countermeasure

Temperature derating considerations (shown below) are recommended at the time of the initial design stage to determine the LED forward operating current (I_F).

[How to design the trigger LED forward current value (I_{FT})]

Design value of trigger LED forward current (I_F) = I_{FT} (maximum value) $\times \alpha 1 \times \alpha 2 \times (\alpha 3)$

$\alpha 1$: LED aging rate

→ Differs by model (the type of LED used).

Refer to the “expected service life” indicated in the catalogue under the precaution page.

$\alpha 2$: Ambient temperature change

→ Refer to the Graph: *Trigger LED Forward Current with Ambient Temperature* indicated in the catalogue.

$\alpha 3$: Safety factor

→ Degree of safety margin for power supply variation and degradation.

(Example) G3VM-401G, at maximum room temperature of 85°C

I_{FT} : 3 mA (maximum rated value, at 25°C)

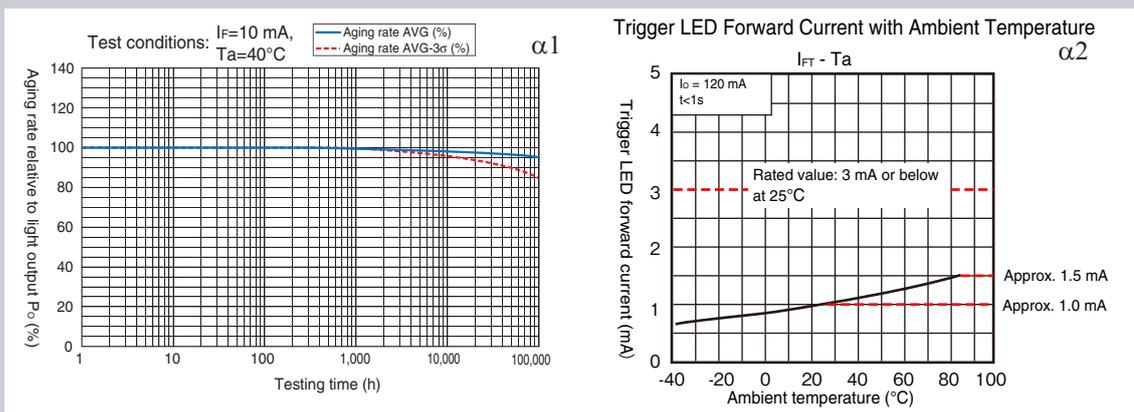
$\alpha 1$: Set for 80% (20% reduction) after 100,000 hours of useful life based on the data of LED's expected life expectancy → $1 \div 0.8 = 1.25$

(When room temperature rises, aging accelerates. Therefore the aging rate increases more at 85°C compared to the data at 40°C. However, the rate will slow down if used under the condition that is lower than the I_F condition of 10 mA. 80% is set considering this point.)

$\alpha 2$: Set the aging rate based on the values of room temperature at 20°C and 85°C referring to the Graph: *Trigger LED Forward Current with Ambient Temperature*

→ $1.5 \text{ mA} \div 1 \text{ mA} = 1.5$

Design value = 3 mA \times 1.25 \times 1.5 ($\times \alpha 3$) = approx. 5.6 mA ($\times \alpha 3$)



Input Circuit Design Guideline (LED aging degradation and ambient temperature)

Lack of LED forward operating current (I_F) caused by “drop in light output due to age-related degradation of input LED” of MOS FET relay and “increased room temperature” may cause the MOS FET relay to malfunction.

Probable cause of failure

Failure event 1. Lack of trigger LED forward current (I_{FT}) due to age-related degradation of input LED

(Case study)

We needed input current of 3.5 mA. So, we selected a model (G3VM-401G) with the maximum trigger LED forward current (I_{FT}) rating of 3 mA ($T_a=25^\circ\text{C}$) with safety margin.

The prototype test results were good, showing normal operation.

Malfunction had occurred after the product was launched into the market and running for 100,000 hours.

(Cause)

Light output stipulated in the Graph: *Expected Aging Data* had diminished during actual use, increasing the trigger LED forward current (I_{FT}) which led to the shortage in LED forward current and ultimately causing malfunction.

(Conclusion)

Light output diminishes according to the input side of the LED's running time as shown in the graph below.

The graph indicates approximately 20% of light output drop when running for 100,000 hours at $I_F=10$ mA.

I_{FT} apparently increases by 25% (*) when the light output diminishes by 20%.

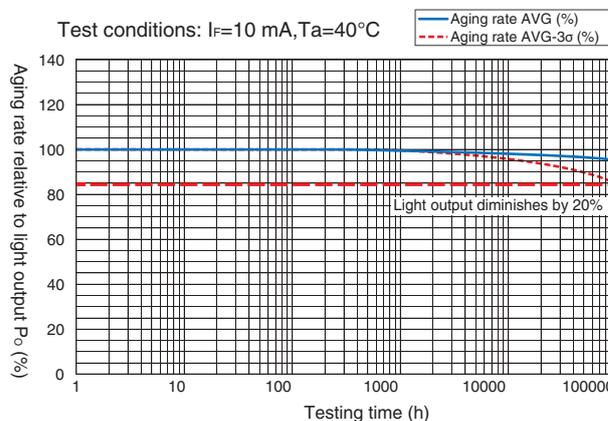
The trigger LED forward current (I_{FT}) increases to 3.75 mA causing lack of LED forward operating current (I_F) of 3.5 mA ultimately causing the product in the market to malfunction.

* Equation

$$1/(100-20) = 1.25 \text{ (125\%)}$$

Example: G3VM-401G

$$I_{FT} = 3 \text{ mA} \rightarrow 3.75 \text{ mA}$$



The input current must be designed based on the maximum rating of the LED forward operation current (I_{FT}) and must take into account the decline in the LED light output associated with the operating time.

Lack of LED forward operating current (I_F) caused by “drop in light output due to age-related degradation of input LED” of MOS FET relay and “increased room temperature” may cause the MOS FET relay to malfunction.

Probable cause of failure

Failure event 2. Relay stopped working due to the lack of LED forward current (I_F) under high temperature condition.

(Case study)

We selected a model with 1 mA of design current (input side) because the standard value of the trigger LED forward current was 1 mA ($T_a=25^\circ\text{C}$).

The prototype test results were good, showing normal operation.

(The MOS FET relay during the trial test was used under room temperature of 25°C)

Malfunction occurred after the product was launched into the market.

| Item | Symbol | --- | --- | Unit |
|-----------------------------|----------|----------|-----|------|
| Trigger LED forward current | I_{FT} | Standard | 1 | mA |
| | | Maximum | 3 | |

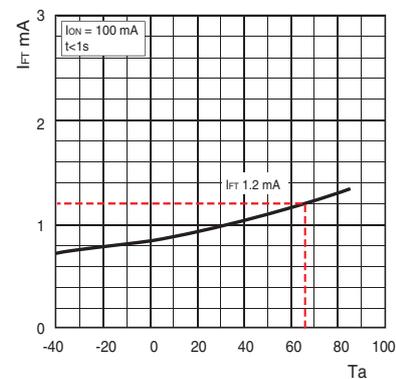
(Cause)

The MOS FET relay was used under actual room temperature of 60°C causing the trigger LED forward current (I_{FT}) stipulated in the Graph: *LED Current with Ambient Temperature* to rise and the LED forward current (I_F) to fall short resulting to malfunction.

(Conclusion)

The trigger LED forward current (I_{FT}) changes according to ambient temperature as shown on the right graph.

The MOS FET relay used this time under ambient temperature of 60°C is specified at 1.2 mA for I_{FT} exceeding the current of 1 mA ($1\text{ mA} < 1.2\text{ mA}$) causing the product in the market to malfunction.

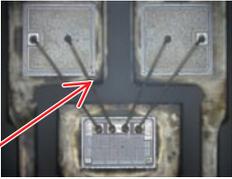
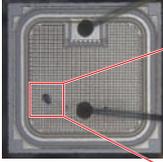
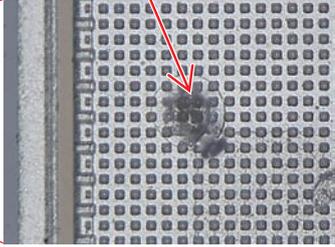
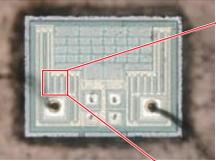
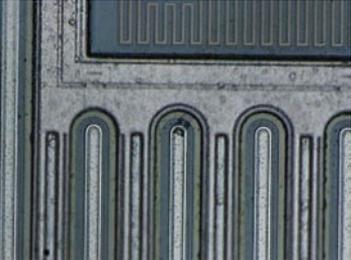
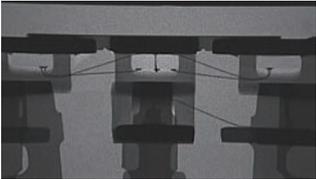
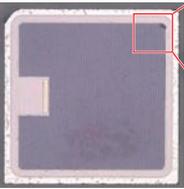
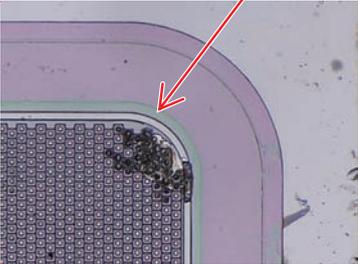


Countermeasure

The input current must be designed based on the maximum value of the trigger LED forward current and taking into account the changes in ambient temperature.

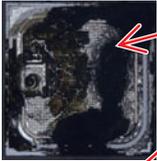
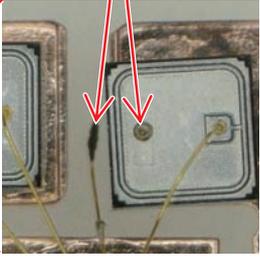
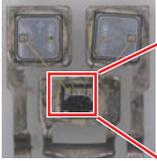
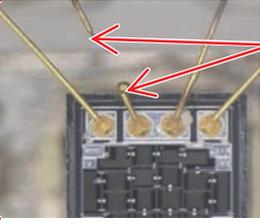
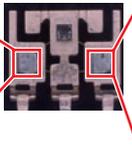
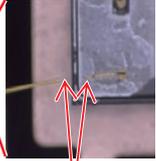
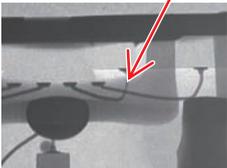
Photos of Failure Event (Output)

Output short circuit fault

| Failure characteristics | Condition of output element |
|---|--|
|  <p data-bbox="464 779 587 801">Short circuit</p> |  <p data-bbox="635 676 758 698">Burn damage</p>   <p data-bbox="1193 676 1316 698">Burn damage</p> |
| X-ray image of the interior |   |
|  <p data-bbox="325 1429 459 1451">No anomalies</p> |   <p data-bbox="1305 1272 1428 1294">Burn damage</p> |

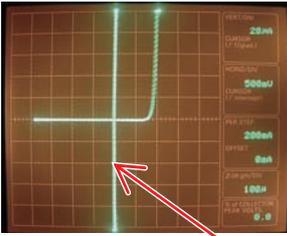
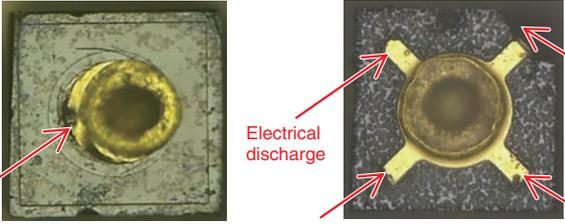
Photos of Failure Event (Output)

Output open circuit fault

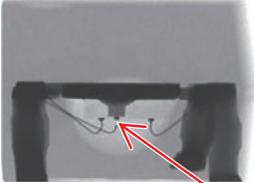
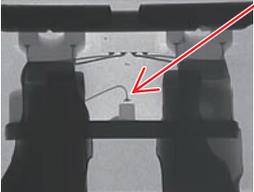
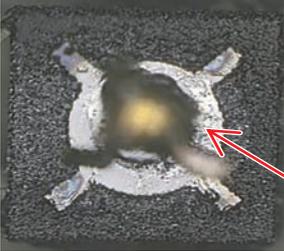
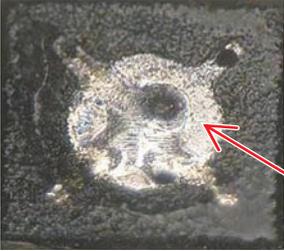
| Exterior | Condition of output element |
|--|---|
| <p data-bbox="240 555 347 577">Burnt resin</p>  <p data-bbox="347 824 539 846">Broken resin (crack)</p>  |  <p data-bbox="991 551 1174 573">Burn damage (chip)</p> <p data-bbox="1094 577 1158 600">Melted</p>    <p data-bbox="1262 943 1326 965">Melted</p>  <p data-bbox="823 1346 887 1368">Melted</p>   <p data-bbox="1150 1346 1214 1368">Melted</p> |
| <p data-bbox="240 1070 520 1093">X-ray image of the interior</p> | |
|  <p data-bbox="448 1200 512 1223">Melted</p>  <p data-bbox="304 1447 368 1469">Cracked</p> <p data-bbox="384 1451 448 1473">Melted</p> | |

Photos of Failure Event (Input)

Input short circuit fault

| Failure characteristics | Condition of input light-emitting element |
|--|--|
|  <p data-bbox="464 763 587 790">Short circuit</p> |  <p data-bbox="628 701 735 728">Burn damage</p> <p data-bbox="999 633 1106 660">Electrical discharge</p> <p data-bbox="1347 566 1453 593">Chip crack</p> <p data-bbox="1043 734 1182 761">Electrical discharge</p> <p data-bbox="1347 734 1453 761">Electrical discharge</p> |

Input open circuit fault

| Failure characteristic | Condition of input light-emitting element |
|---|--|
|  <p data-bbox="395 1205 459 1232">Melted</p>  <p data-bbox="453 1256 603 1283">Electrode to float</p> |  <p data-bbox="1171 1173 1358 1200">Electrode to melt</p>  <p data-bbox="1171 1464 1358 1491">Electrode to melt</p> |

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